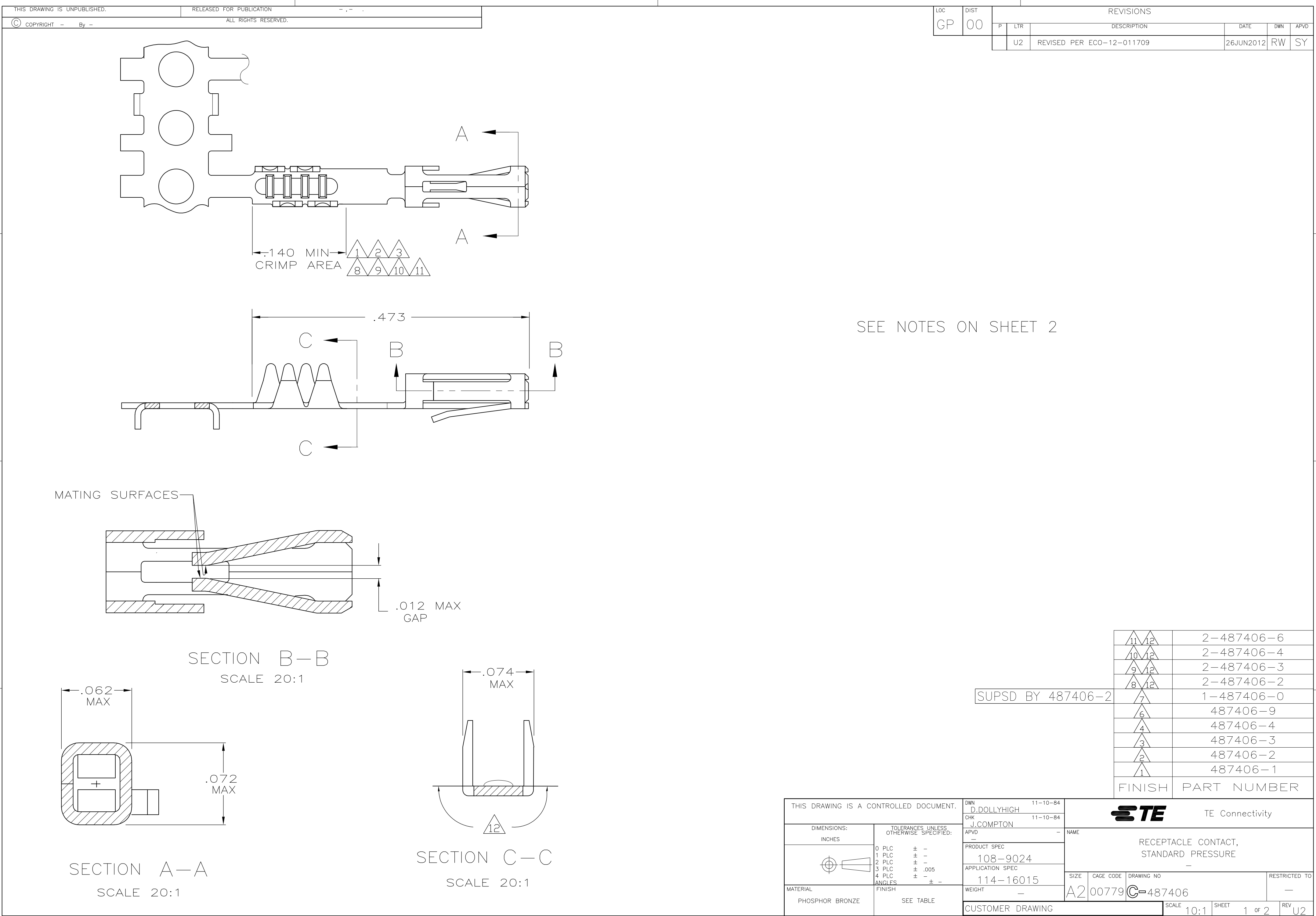
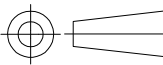




LOC	DIST	REVISIONS					
GP	00	P	LTR	DESCRIPTION	DATE	DWN	APVD
			—	SEE SHEET 1	—	—	—

- 1
- PREPLATED WITH NICKEL UNDERPLATE .000050 THK ON ENTIRE CONTACT WITH GOLD .000015 THK ON MATING AREA AND PLATED WITH BRIGHT TIN-LEAD .000100 THK IN CRIMP AREA,
-OR-
NICKEL .000050 MIN THK UNDERPLATE ON ENTIRE CONTACT, GOLD FLASH OVER PALLADIUM-NICKEL, .000015 MIN TOTAL THK ON MATING SURFACES AND BRIGHT TIN/LEAD .000100 MIN THK IN CRIMP AREA.
- 2
- PREPLATED WITH NICKEL UNDERPLATE .000050 THK ON ENTIRE CONTACT WITH GOLD .000030 THK ON MATING AREA AND PLATED WITH BRIGHT TIN-LEAD .000100 THK IN CRIMP AREA,
-OR-
NICKEL .000050 MIN THK UNDERPLATE ON ENTIRE CONTACT, GOLD FLASH OVER PALLADIUM-NICKEL, .000030 MIN TOTAL THK ON MATING AREA AND BRIGHT TIN/LEAD .000100 MIN THK ON CRIMP AREA.
- 3
- PREPLATED WITH NICKEL UNDERPLATE .000050 THK ON ENTIRE CONTACT WITH GOLD .000050 THK ON MATING AREA AND PLATED WITH BRIGHT TIN-LEAD .000100 THK IN CRIMP AREA,
-OR-
NICKEL .000050 MIN THK UNDERPLATE ON ENTIRE CONTACT, GOLD FLASH OVER PALLADIUM-NICKEL, .000050 MIN TOTAL THK ON MATING AREA AND BRIGHT TIN/LEAD .000100 MIN THK ON CRIMP AREA.
- 4
- .000100 BRIGHT TIN-LEAD OVER .000050 PRE-PLATED NICKEL UNDERPLATE ON ENTIRE CONTACT.
5. MATING POST LENGTH ACCEPTED:
SINGLE ROW HOUSINGS .220-.323
DOUBLE ROW HOUSINGS .235-.323
- 6
- PREPLATED WITH NICKEL UNDERPLATE .000050 THK ON ENTIRE CONTACT WITH GOLD .000050 THK ON MATING AREA AND GOLD FLASH OVER ENTIRE CONTACT,
-OR-
NICKEL .000050 MIN THK UNDERPLATE ON ENTIRE CONTACT, GOLD FLASH OVER PALLADIUM-NICKEL, .000050 MIN TOTAL THK ON MATING AREA AND GOLD FLASH OVER ENTIRE CONTACT.
- 7
- PREPLATED WITH NICKEL UNDERPLATE .000050 THK ON ENTIRE CONTACT WITH GOLD .000030 THK ON MATING AREA AND PLATED WITH GOLD .000030 THK ON ENTIRE CONTACT EXCEPT .000003 MIN THK PERMISSIBLE ON INTERIOR OF CONTACT BOX EXCLUSIVE OF MATING AREA.
- 8
- PREPLATED WITH NICKEL UNDERPLATE .000050 MIN THK ON ENTIRE CONTACT WITH GOLD .000015 MIN THK ON MATING AREA AND PLATED WITH GOLD FLASH IN CRIMP AREA,
-OR-
NICKEL .000050 MIN THK UNDERPLATE ON ENTIRE CONTACT, GOLD FLASH OVER PALLADIUM-NICKEL, .000015 MIN TOTAL THK ON MATING AREA AND GOLD FLASH IN CRIMP AREA.
- 9
- PREPLATED WITH NICKEL UNDERPLATE .000050 MIN THK ON ENTIRE CONTACT WITH GOLD .000030 MIN THK ON MATING AREA AND PLATED WITH GOLD FLASH IN CRIMP AREA,
-OR-
NICKEL .000050 MIN THK UNDERPLATE ON ENTIRE CONTACT, GOLD FLASH OVER PALLADIUM-NICKEL, .000030 MIN TOTAL THK ON MATING AREA AND GOLD FLASH IN CRIMP AREA.
- 10
- PRE-PLATED WITH NICKEL UNDERPLATE .000050 THICK ON ENTIRE CONTACT WITH GOLD FLASH IN CRIMP AREA AND .000100 MIN TIN ON MATING AREA.
- 11
- PRE-PLATED WITH NICKEL UNDERPLATE .000050 THICK ON ENTIRE CONTACT WITH GOLD .000050 THICK ON MATING AREA AND PLATED WITH GOLD FLASH IN CRIMP AREA,
-OR-
NICKEL .000050 MIN THK UNDERPLATE ON ENTIRE CONTACT, GOLD FLASH OVER PALLADIUM-NICKEL, .000050 MIN TOTAL THK ON MATING AREA AND GOLD FLASH IN CRIMP AREA.
- 12
- GOLD PLATING MAY OR MAY NOT BE PRESENT ON THE BOTTOM OF THE CRIMP BARREL IN THIS AREA.

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN D.DOLLYHIGH 11-10-84		 TE Connectivity					
		CHK J.COMPTON 11-10-84							
DIMENSIONS: INCHES		TOLERANCES UNLESS OTHERWISE SPECIFIED:		NAME RECEPTACLE CONTACT, STANDARD PRESSURE —					
		APVD —							
		PRODUCT SPEC 108-9024							
		APPLICATION SPEC 114-16015							
		SIZE A2							
MATERIAL PHOSPHOR BRONZE		FINISH SEE TABLE		CAGE CODE 00779		DRAWING NO C=487406		RESTRICTED TO —	
		CUSTOMER DRAWING		SCALE 10:1		SHEET 2 of 2		REV U2	

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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